

ET1895

End Termination

Description

ET1895 is a nickel plateable silver end termination designed to be compatible on Multilayer ceramic chip capacitors (NPO and X7R bodies). Nickel plating can be done without pre-plate processing due to the low glass content on the fired surface. The rheology of ET1897 is suitable for machine dipping.

Key Features

- Nickel plateable no pre-plate processing Low usage excellent coverage uniformity Dense fired microstructure



This picture does not show the packaging of ET1895 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties

Viscosity	55 – 65 Kcps Brookfield RVT SC4 – 14 spindle, 6R utility cup at 10 rpm, 25 °C
Solids	76.5 ± 1.5 %
Alloy Ratio	100
Metal	Ag

Recommended Processing Guide

Drying Temperature	150 – 180 °C for 8 minutes Peak temperature of 175 °C for 2 minutes 20 minutes total cycle time
Process Temperature (TDS)	700 – 800 °C peak temperature Dwell time at temp. 5 – 7 minutes
Recommended Thinner	RV-372

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Warranty

6 months

Storage

Store in a dry location at 5 – 25 °C.

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